



Product Change Notification: JPZA-21GJBI008

Date:

27-Jul-2026

Product Category:

Voltage References

Notification Subject:

CCB 8390 Final Notice: Qualification of MTAI as an additional assembly site for selected MCP1501 device family available in 8L SOIC (3.90mm) package.

Affected CPNs:

[JPZA-21GJBI008_Affected_CPN_07272026.pdf](#)
[JPZA-21GJBI008_Affected_CPN_07272026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for selected MCP1501 device family available in 8L SOIC (3.90mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	UTAC Thai Limited (UTL-2) (NSEB)	UTAC Thai Limited (UTL-2) (NSEB)	Microchip Technology Thailand	Yes

			(HQ) (MTAI)	
Wire Material	Au	Au	CuPdAu	Yes
Die Attach Material	2200D (PFAS)	2200D (PFAS)	QMI519 (PFAS-Free)	Yes
Molding Compound Material	G600	G600	G600V	Yes
Lead-Frame Material	CDA194	CDA194	CDA194	No
Lead-Frame Paddle Size	80x80 mils	80x80 mils	90x90 mils	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 12 October 2026 (date code: 2642)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	October 2026				
Work Week	27	28	29	30	31		40	41	42	43	44
Qual Report Availability					X						
Final PCN Issue Date					X						
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB# 7841.

Revision History: July 27, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_JPZA-21GJBI008_Qualification_Report_CCB7841.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MCP1501-40E/SN
MCP1501-33E/SN
MCP1501-30E/SN
MCP1501-25E/SN
MCP1501-20E/SN
MCP1501-18E/SN
MCP1501-12E/SN
MCP1501-10E/SN
MCP1501T-40E/SN
MCP1501T-33E/SN
MCP1501T-18E/SN
MCP1501T-25E/SN
MCP1501T-20E/SN
MCP1501T-30E/SN
MCP1501T-12E/SN
MCP1501T-10E/SN



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: JPZA-21GJBI008

Date: February 3, 2026

Qualification of MTAI as an additional assembly site for selected MCP1501 device family available in 8L SOIC (3.90mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MTAI as an additional assembly site for selected MCP1501 device family available in 8L SOIC (3.90mm) package.

CN:	E000289334
QUAL ID:	R2501376 Rev. A
MP CODE:	370044D3X001
Part No.:	MCP6009-E/SL
Bonding No.:	BD-003737 Rev.01
CCB No.:	7841

Lead Frame

Paddle Size:	95 x 155 mils
Material:	CDA194
Surface:	Bare Cu
Process:	Stamped
Lead Lock:	No
Part Number:	10101405
Plating Composition:	Matte Tin

Bond Wire

Wire:	CuPdAu wire
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Die Attach Material

Epoxy:	QMI519
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Mold Compound

Mold Compound:	G600V
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Package

Type:	14L SOIC
Package Size:	150 mils

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI263001192.000	TC08925381309.B00	2543Q2P
MTAI263001448.000	TC08925381309.B00	2543QRY
MTAI263001450.000	TC08925381309.B00	2543QSA

Result: **Pass**

Conclusion:

14L SOIC (150 mils) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C and 125°C System: ETS300	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/IPC/JEDEC J-STD-020E	693	693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH		693	693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243		693	693		
	Electrical Test: +25°C and 125°C System: ETS300		693(0)	0/693	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104	231	231		
	Electrical Test: + 125°C System: ETS300		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams)		15(0)	0/15	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118	231	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: ETS300		231(0)	0/231	Pass	77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22-A110	231	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 125°C System: ETS300		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven	JESD22-A103	135	135		45 units /lots
	Electrical Test: +25°C and 125°C System: ETS300		135(0)	0/135	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000	J-STD-002	22	22		
	Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D		22(0)	22		
	Visual Inspection: External Visual Inspection			0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (>3.00 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>12.60 grams)	CDF-AEC-Q100 -001	30(0) Bonds	0/30	Pass	